### **COMPONENT SPECIFICATION**

版次:第3版 MAX ECHO

N A	Ferrite Chip EMI Suppressors	COMPO	OSITE SPECIFICATION	1/_
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#### 1. SCOPE

This specification applies to the ACMS-3216 series Ferrite Chip EMI suppressors.

#### 2. STANDARD ATMOSPHERIC CONDITIONS

Unless otherwise specified the standard range of atmospheric conditions for making measurements and tests is as follows:

Ambient temperature :  $20\pm15^{\circ}$ C Relative humidity :  $30\sim70\%$ 

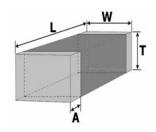
If there may be any doubt on the results, measurements shall be made within the following limits :

Ambient temperature : 25±5°C Relative humidity : 30~70%

3. RATINGS

PART NO	IMPEDANCE ( $\Omega$ )	DC RESISTANCE	RATED CURRENT
PART NO	AT 100 MHz 500mV	$(\Omega)$ Max	(mA) Max
ACMS321611A600	60±25%	0.03	3000

#### 4. DIMENSION



OPERATING TEMP. RANGE:  $-55^{\circ}$ C ~  $+125^{\circ}$ C STORAGE TEMP. RANGE:  $-10^{\circ}$ C ~  $+40^{\circ}$ C

TYPE	L	W	T	Α
ACMS-3216	3.2±0.2	1.6±0.2	1.1±0.2	0.4~1.0
7101110 0210	(.126±.008)	(.063±.008)	(.043±.008)	

### 5. The place of origin:

Taichung, Taiwan

HISTORY	DATE		REVISION	SIGN.	SIGN.
PLANNED BY	CHECKED BY	APPROVED BY		1	
JSHING	esu	Chi Chi Huang	鈺鎧文件中心 發行章		

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				'
	ACMS32161	1A600		
100				
$(\Omega)$				
80				
80			7	
60			Z	
00			<b>D</b>	
40			<b>R</b>	
40		$\mathbb{Z}[[]]$	_x	-
20		_+	^	
20				
				<u> </u>

Frequency(MHz)

100

1000

10

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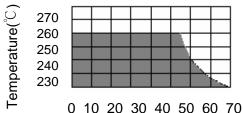
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- 6) Reflow soldering conditions
- Pre—heating should be in such a way that the temperature difference between solder and ferrite surface is limited to 150°C max. Also cooling into solvent after soldering should be in such a way that the temperature difference is limited to 100°C max.
  - Unenough pre—heating may cause cracks on the ferrite, resulting in the deterioration of product quality.
- Products should be soldered within the following allowable range indicated by the slanted line.
   The excessive soldering conditions may cause the corrosion of the electrode, When soldering is repeated, allowable time is the accumulated time.



Temperature Profile

Temperature [℃]>	Main heating E 230°C E Pre-heating 180 Normal temperature A B C D
	Time [sec]

A	Slope of temp. rise	1 to 5	:	°C/sec
В	Heat time	50 to 150		sec
ь	Heat temperature	120 to 180		$^{\circ}\!\mathbb{C}$
С	Slope of temp. rise	1 to 5		°C/sec
D	Time over 230°ℂ	90~120		sec
Е	Peak temperature	255~260		$^{\circ}\!\mathbb{C}$
E	Peak hold time	10 max.		sec
	No. of mounting	3	:	times

(Melting area of solder)

6-1 Reworking with soldering iron

Preheating	150°C, 1 minute
Tip temperature	280°C max
Soldering time	3seconds max.
Soldering iron output	30w max.
End of soldering iron	§ 3mm max.

Reworking should be limited to only one time.

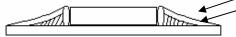
Note: Do not directly touch the products with the tip of the soldering iron in order to prevent the crack on the ferrite material due to the thermal shock.

6-2 Solder Volume

Upper Limit

Solder shall be used not to be exceed the upper limits as shown below.

Recommendable



Accordingly increasing the solder volume, the mechanical stress to product is also increased. Exceeding solder volume may cause the failure of mechanical or electrical performance.

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#### **7 EQUIPMENT**

#### 7-1 IMPEDANCE

Impedance shall be measured with HP  $-4286\mathrm{A}$  impedance analyzer or equivalent system

#### 7-2 DC RESISTANCE

DC resistance shall be measured using HP 4338 digital mili — ohm meter with 4 terminal method.

#### 8.MECHANICAL CHARACTERISTICS

	CAL CHARACTERISTICS	T
ITEM	Specification	TEST CONDITIONS
TERMINAL	Without deformation cases	Solder chip on PCB and applied 10N
STRENGTH	impedance shall be satisfied ± 30%	(1.02Kgf) for 10 sec
	DC resistance shall be satisfied.	CHIP BEAD
		Gloss sport PGB
		F
Substrate	Without deformation cases,	After soldering a chip to a test substrate,
bending test	·	bend the substrate by 3mm hold for 10s
· ·	DC resistance shall be satisfied.	and then return.
		Soldering shall be done in accordance
		with the recommended PC board pattern
		and reflow soldering.
		unit : mm
		45 45
RESISTANCE	No visible damage	Solder Temp. : 265±3°C
TO SOLDER	Electrical characteristics and mechanic	Immersion time : 6±1 sec
HEAT	characteristics shall be satisfied.	Preheating : $100^{\circ}$ to $150^{\circ}$ , 1 minute.
		Measurement to be made after keeping at room
	Consult standard MIL-STD-202	temp for 24±2 hrs.
	METHOD 210	Solder : Sn-3Ag-0.5Cu
SOLDER-	95% min. coverage of all	Solder temp. : 240±5°C
ABILITY	metabolised area	Immersion time : 3±1 sec
		Solder : Sn-3Ag-0.5Cu
	Consult standard J-STD-002	

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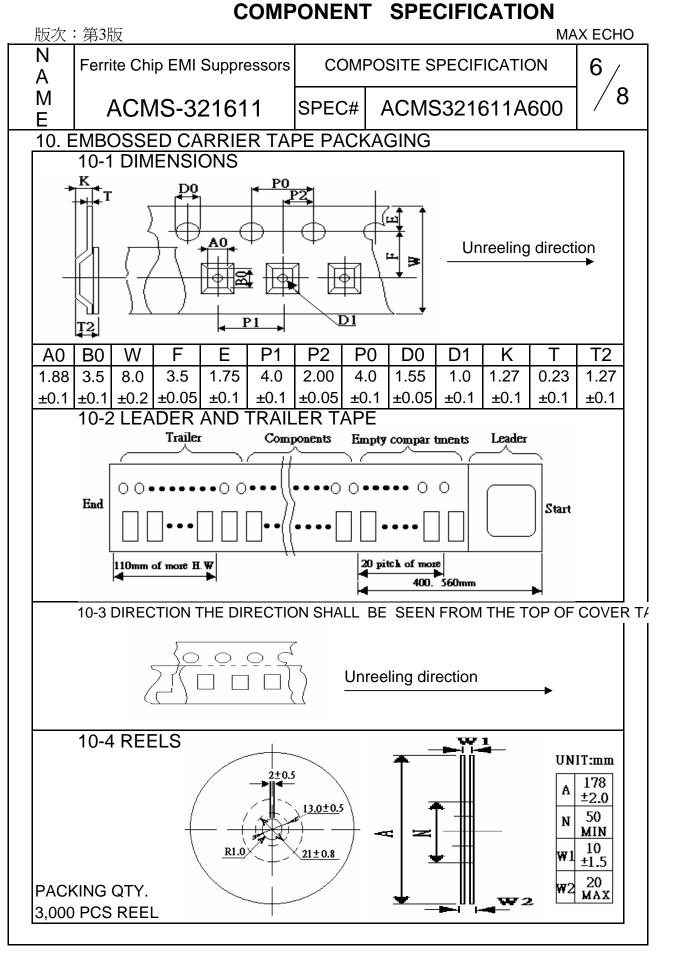
- 9-1 HIGH TEMPERATURE RESISTANCE
  - a. Performance specification
  - 1. Appearance: no mechanical damage
  - 2.Impedance shall be with ±30% of the initial value
  - DC resistance shall be satisfied
  - b.Test condition
  - 1.Temperature125°C±2°C
  - 2.Applied current: Rated current(maximum value)
  - 3.Testing time: 1008±12hrs
  - 4.Measurement: After placing at room ambient temperature for 24 hours minimum
- 9-2 HUMIDITY RESISTANCE
  - a.Performance specification
  - 1.Appearance: no mechanical damage
  - 2.Impedance:within ±30% of initial value
  - 3.DC resistance shall be satisfied
  - b.Test condition
  - 1.Humidity: 90 to 95% RH

  - 2.Temperature : 60±2°C 3.Applied current : Rated current (maximum value)
  - 4. Testing time: 1008±12hours
  - 5.Measurement: After placing at room ambient temperature for 24 hours minimum
- 9-3 TEMPERATURE CYCLE
  - a.Performance specification
  - 1.Appearance: no mechanical damage
  - 2.Impedance:within ±30% of initial value
  - 3. DC resistance shall be satisfied
  - b.Test condition
  - 1.Temperature -55°C,+125°C kept stabilized for 30 minutes each
  - 2.Cycle: 100 cycles
  - 3.Measurement: After placing for 24 hours minimum at room ambient temperature
  - 4. step1. -55°C temp±3°C 30±3 minutes
    - step2. Standard atmospheric conditions 5s or less
- step3. +125°C temp±2°C 30±3 minutes step4. Standard atmospheric conditions 5s or less 9-4 LOW TEMPERATURE STORAGE LIFE TEST

- a.Performance specification
- 1.Appearance: no mechanical damage
- 2.Impedance shall be with ±30% of the initial value
- 3. DC resistance shall be satisfied
- b.Test condition
- 1.Temperature -55°C ±2°C
- 2.Testing time: 1008±12hours
- 3.Measurement: After placing for 24 hours minimum at room ambient temperature

#### 9-5 THERMAL SHOCK

- a.Performance specification
- 1. Appearance: no mechanical damage
- 2.Impedance shall be with ±30% of the initial value
- b.Test condition
- 1.Temperature -55°C,+125°C kept stabilized for 30 minutes each
- 2.Cycle: 100 cycles
- 3.Measurement: After placing for 24 hours minimum at room ambient temperature 9-6 VIBRATION TEST
  - a.Performance specification
  - 1. Appearance: no mechanical damage
  - 2.Impedance shall be with ±30% of the initial value
  - b.Test condition
  - 1.Waveform:Sine wave
  - 2.Frequency:10~55~10 Hz
  - 3.Sweep time:1min
  - 4.Amplitude:1.5mm(peak-peak)
  - 5.Direction:X,Y,Z(3 axes)
  - 6.Duration: 2 hrs./axis,total 6 hrs.

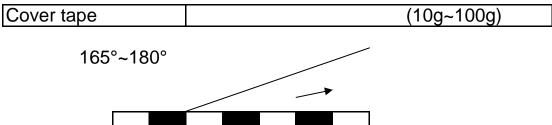


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# MAX ECHO 鈺鎧科技股份有限公司規格標準書 COMPONENT SPECIFICATION

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#### 10-5 PEELING STRENGTH OF COVER TAPE



Test condition

1) peel angle: 165°~180° vs carrier tape

2) peel speed: 300mm/min

11.PACKAGING

- 1) Tape & Reel packaging in composite specification 6/8
- 2) Reel and a bag of desiccant shall be packed in Nylon or plastic bag
- 3) Maximum of 5 bags shall be packaged in a inner box
- 4) Maximum of 6 inner box shall be packaged in a outer box

#### 12.Reel Label

Producing the goods label needs to indicate (1) Pb Free (2) RoHS Compliant

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#### 13. STORAGE

- 13-1The solderability of the external electrode may be deteriorated if packages are stored where they are exposed to high humidity. Packages must be stored at 40°C or less and 70% RH or less.
- 13-2 The solderability of the external electrode may be deteriorated if packages are stored where they are exposed to dust or harmful gas (hydrogen chloride, sulfurous acid gas or hydrogen sulfide).
- 13-3 Packaging material may be deformed if packages are stored where they are exposed to heat or direct sun—light.
- 13-4 Minimum packages, such as polyvinyl heat—seal packages shall not be opened until just before they are used. If opened, use the reels as soon as possible.
- 13-5 Solderability specified in composite specification 4/8 shall be for 6 months from the date of delivery on condition that they are stored at the environment specified clause 13-1 & 13-2.

For those parts which passed more than 6 months shall be checked solderability before it is used.